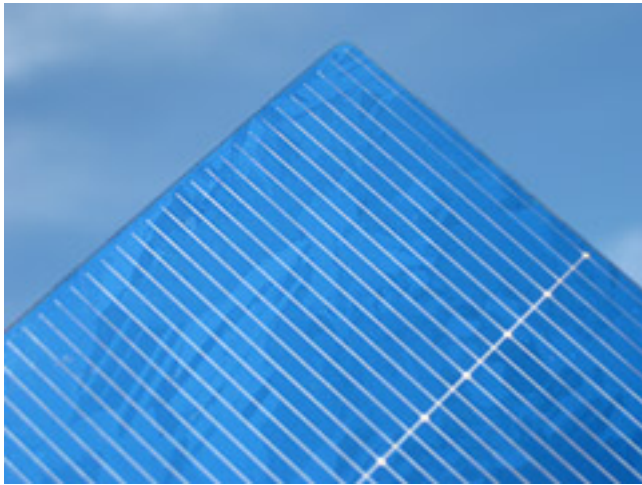


Metallization materials tout desirable adhesion



DuPont Microcircuit Materials has launched its next-generation back side silver material for high-efficiency solar cells. DuPont™ Solamet PV51x series photovoltaic metallization paste products are tabbing conductors made with a formulation that enables cell makers to use up to 25 percent less material and delivers comparable electrical performance versus the leading incumbent, according to the company. This helps reduce dependence on silver metals and offsets some of the impact that rising silver prices have on the cost of producing solar cells and modules. The company asserts all the Solamet PV51x Series products provide an excellent printability window; ability to co-fire with current Solamet front side silver pastes; a superior adhesion window; reduced laydown; reduced tab footprint; and are made without lead or cadmium. The new Solamet PV51G photovoltaic metallization back side paste is a highly conductive, solderable silver composition, developed to provide desirable adhesion when used in conjunction with back side aluminum compositions.

DuPont Microcircuit Materials

<http://photovoltaics.dupont.com> [1]

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http://www.ecnmag.com/product-releases/2012/05/metallization-materials-tout-desirable-adhesion?qt-most_popular=0

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[1] <http://photovoltaics.dupont.com>